The world's lowest power x86 cloud processor¹ just got more efficient

AMD Opteron[™] 4200 Series Processor



KEY FEATURES

- → New Core Architecture drives more core density and greater throughput
- → AMD Turbo CORE Technology allows processors to independently boost their clock speeds, scaling frequency up 300MHz-1.2GHz automatically to respond to the need for more application performance²
- → C6 Power State reduces processor power consumption at active idle by up to 3970^3
- → AMD Virtualization[™] (AMD-V[™]) Technology 2.0 heightens virtualization efficiency with new enhancements to the AMD-V[™] suite of virtualization to optimize data center rack space and help minimize management tasks

END USER BENEFITS

Designed for enterprise workloads while still delivering a performance punch

- → A 33% increase in core count packs in plenty of processing performance into a smaller, more efficient, 8-core design while maintaining very aggressive power/thermal ranges^{4,5}
- → Power per core that shatters the 5W/core mark, a new record for an enterprise-class x86 processor¹
- → New power management capabilities allow for larger parts of the processor to be almost completely powered off when not being used, dramatically reducing idle core power consumption by up to 39% over the previous generation of processors and allowing active cores to run at a higher frequency³
- → AMD Turbo CORE technology takes advantage of additional power headroom to digitally boost all cores simultaneously by up to 300MHz and can boost up to 1.2GHz when only half of the cores are active², allowing applications to finish tasks quickly and return to lower power states
- → Straight-through computing helps ensure that there are not bottlenecks or compromises as up to eight threads get their own dedicated core when workload demands increase with maximum memory channel and I/O speed (across all SKUs/ price points) helping to ensure that there are no bottlenecks or feature compromises unlike Intel, who purposely throttles down capabilities

Delivering new levels of enterprise scalability for demanding cloud applications and SMB/Infrastructure applications

 \rightarrow Scale your cloud workload with up to 8 cores in a low power processor

- → Efficiently scales performance/watt based on the innovative modular design and aggressive power capabilities
- → New power saving features, like TDP Power Cap, put the customer in control of more aspects of power efficiency than ever before on AMD Opteron[™] processor-based servers
- → Up to 8 cores and more processing throughput⁶ than the previous generation helps your cloud easily scale within the most fluid and spiky processing environments, easily responding to the elastic needs of clouds

Bringing unparalleled efficiency to your processing, power and financial budgets

- → The lowest enterprise-class power per core with up to 8 cores in only 35W of power, shattering the previous record¹
- → 32nm design and a smaller die⁴ drive more efficiency at the processor level to help ensure you are maximizing your performance per watt per square foot
- → Virtualized infrastructure deployments can enjoy 33% more VMs in the same power and thermal ranges⁵ thanks to the new AMD-V[™] virtualization features, allowing small/medium businesses to grow with their business needs on a single virtualized platform
- → New instructions make processing technical software commands more efficient, allowing for more computing per cycle, which helps drive down processing requirements so that web/cloud applications can more easily process their workload and return to lower power states
- → Easy on your budget through both unprecedented value and low power consumption, helping hold down not only acquisition costs but also the long-term total cost of ownership

1 As of March 16, 2012 AMD Opteron[™] processor Models 4200 EE have the lowest known power per core of any x86 server processor, at 35W TDP (35W/8 = 4.375W/core). Intel's lowest power per core server processor, Intel Xeon E5-2650L, is 70W TDP (70W/8 = 8.75W/core). See www. Intc.com/pricellstc/m as of 3/16/12. Previous record held by AMD Opteron processor Models 4100 EE at 35W TDP / 6 cores = 5.83 W/core. SVR-58

5 Based on 8-core AMD Opteron 4200 Series processors at 35W, 65W and 95W TDP compared to 6-core AMD Opteron 4100 Series processors at 35W, 65W and 95W TDP when utilizing the 1 VM per core loading rule, SVR-59 6 SPEC and SPECint are registered trademarks of the Standard Performance Evaluation Corporation. The results reflect results published onhttp://

Since Statistics Departments of the statistic of the comparison presented above is based on the best performing two-socket servers using AMD Opteron[®] processor Models 4184 and 4284. For the latest SPECint[®]_rate2006 results, visit http://www.spec.org/opu2006/results/ as d 4/12/L. The comparison presented above is based on the best performing two-socket SS using 2 x AMD Opteron[®] processor Models 4184 and 4284. For the latest SPECint[®]_rate2006 results, visit http://www.spec.org/opu2006/results/ as SS using 2 x AMD Opteron[®] processor Models 4284 in Del PowerEdge RSIS server, 32 GB (4 x 8 GB 2Rx4 PC3-12800R-11, ECO), Red Hat Enterprise Linux[®] Server release 61, Kernel 2.632-131.015.616386 <u>64</u>, C/C+++ Version 42.52 of x88 Open64 Compiler Sulte (from AMD), http://www.spec.org/ opu2006/results/res20104/opu2006-2011206-19137.html; 237 using 2 x AMD Opteron[®] processors Model 4184 in Del PowerEdge R4IS server, 32GB (8 x 4GB DDR3-1333) memory, SUSE Linux[®] Enterprise Server 11, x86 Open64 4.2.4 Compiler Sulte, http://www.spec.org/opu2006/results/ res2010q4/opu2006-20100027-13483.html; SVR-120



² AMD Opteron 4200 Series processors experience all core boost of up to 300 MHz (P2 base to P1 boost state) and up to 1.2 GHz max turbo boost (half or fewer cores boost from P2 to P0 boost state), SVR-63

³ Based on testing in AMD Performance Labs as of March 2012, an AMD Opteron⁷ processor model 474 (6-core 2.36Hz) consumes 6.47W in the active idle CIE power state with each AMD opteron⁷ processor model 4284 (8-core 3.06Hz) consumes only 3.977W in the active idle CIE power state with new C6 power gating employed. System configuration: "Kruger-P" reference design kit, 32dB (4x 8GB DDR3-IO6) memory, Segate ST3500415AS SATA disk drive, Microsoft[®] Windows Server 2008 X4 Enterprise Edition R2 SPI. SVR-62
4 Based on AMD Optioner of Do Series processor at 546 mm Vs. AMD Option 400 Series processor at 366 mm.

AMD Opteron[™] 4200 Series Processor Quick Reference Guide

AMD Opteron[™] 4200 Series Processor Product Specifications

| Model Number | Core Count | Core Frequency | All Core Boost Frequency | AMD Turbo CORE Max Frequency | L2 Cache | L3 Cache | TDP |
|-----------------|------------|-------------------|-----------------------------|------------------------------------|----------|--------------------------------|-----------------------------|
| 4284 | 8 | 3.0 GHz | 3.3 GHz | 3.7 GHz | 4 x 2 MB | 8 MB | 95W |
| 4280 | 8 | 2.8 GHz | 3.1 GHz | 3.5 GHz | 4 x 2 MB | 8 MB | 95W |
| 4276 HE* | 8 | 2.6 GHz | 2.9 GHz | 3.6 GHz | 4 x 2 MB | 8 MB | 65W |
| 4274 HE | 8 | 2.5 GHz | 2.8 GHz | 3.5 GHz | 4 x 2 MB | 8 MB | 65W |
| 4256 EE | 8 | 1.6 GHz | 1.9 GHz | 2.8 GHz | 3 x 2 MB | 8 MB | 35W |
| 4240* | 6 | 3.4 GHz | 3.6 GHz | 3.8 GHz | 3 x 2 MB | 8 MB | 95W |
| 4238 | 6 | 3.3 GHz | 3.5 GHz | 3.7 GHz | 3 x 2 MB | 8 MB | 95W |
| 4234 | 6 | 3.1 GHz | 3.3 GHz | 3.5 GHz | 3 x 2 MB | 8 MB | 95W |
| 4230 HE* | 6 | 2.9 GHz | 3.2 GHz | 3.7 GHz | 3 x 2 MB | 8 MB | 65W |
| 4228 HE | 6 | 2.8 GHz | 3.1 GHz | 3.6 GHz | 3 x 2 MB | 8 MB | 65W |
| 4226 | 6 | 2.7 GHz | 2.9 GHz | 3.1 GHz | 3 x 2 MB | 8 MB SKUs available with Sp | 95W eed Bump Launch 2012 |

AMD Opteron[™] 4200 Series Processor Product Specifications

| Cache Sizes | Total Cache: 16MB (8 core), 14MB (6 core) L1 Cache: 16KB/core + 64 KB instruction/module L2 Cache: 1MB (per core) L3 Cache: 8MB (per socket) |
|--|---|
| Process Technology | 32-nanometer SOI (silicon-on-insulator) technology |
| HyperTransport™ Technology 3.0 | 2X HT3 links with peak bandwidth of 6.4 GT/s per link |
| Memory | Integrated DDR3 memory controller — Up to 51.2 GB/s memory bandwidth per CPU for Socket C32 |
| Number of Channels/ Types of Memory | Dual channel support for U/RDDR3 up to DDR3-1600 and ULV (1.25V) RDDR3 up to DDR3-1333 |
| Die Size | 316 mm ² |
| Packaging | Socket C32 — 1207 Organic Land Grid Array (OLGA) |

New SKUs available with Speed Bump Launch 2012

AMD SR5650, SR5670, SR5690 I/O Hub Product Specifications

| | | | | | | | Specilicatio | | |
|-----------------|---|------------------------------|--|---|---|--------------------------|-----------------------|--------------------|----------------|
| Model Number | Processor Interface | PCI Express® P | Number of PCIe [®] Ports/ engines | Virtualization | Error Detection/Isolation | Max TDP/ Idle (w/c1e) | Process Technology | Package | USB Ports |
| | | | | | | | | | PCI Bus Suppo |
| SR5650 | HyperTransport [™] 3.0 technology (5.2GT/s) | v2.0 | 22 lanes/ 8 engines | AMD-VI (IOMMU 1.26) | HyperTransport error handling, PCIe [®] Advanced Error Reporting, PCIe [®] end-to-end Cycle Redundancy Check | 12.6W/ 5.4W | TSMC 65nm | 29 x 29mm FCBGA | Serial ATA |
| | | | | | | | | | SATA Ports |
| SR5670 | HyperTransport [™] 3.0 technology (5.2GT/s) | 30 lanes/ v2.0 9 engines | | AMD-VI (IOMMU 1.26) | HyperTransport error handling, PCIe [®] Advanced Error Reporting, PCIe [®] end-to-end Cycle Redundancy Check | | TSMC 65nm | 29 x 29mm FCBGA | Max TDP/Idle |
| | | | | | | 15.4W/ 5.75W | | | Process Techno |
| | | | 0 | | | | | | Package |
| | | | | | HyperTransport error handling, | | | | |
| SR5690 | HyperTransport [™] 3.0 technology (5.2GT/s) | v2.0 42 lanes/ 11 engines | AMD-Vi (IOMMU 1.26) | PCIe [®] Advanced Error Reporting, PCIe [®] end-to-end Cycle Redundancy Check | 18W/6.15W | TSMC 65nm | 29 x 29mm FCBGA | | |

AMD SP5100 Southbridge Product Specifications

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|--------------------|---|
| USB Ports | 12 USB 2.0 + 2 USB 1.1 |
| PCI Bus Support | PCI rev 2.3 |
| Serial ATA | AHCI 1.1 SATA 3.0Gb/s with SW RAID Support |
| SATA Ports | 6 (can be independently disabled) |
| Max TDP/Idle | 4W/1W |
| Process Technology | TSMC .13um |
| Package | 528 ball FCBGA, 21x21mm, 0.8mm pitch |
| | |

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